PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT2904948

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DONG IN HA	06/17/2014
DONG MIN PARK	06/17/2014
SEUNG SHIK SHIN	06/17/2014
KYUONG SIK CHIN	06/17/2014

RECEIVING PARTY DATA

Name:	CHEIL INDUSTRIES INC.	
Street Address:	58 GUMI-DAERO	
Internal Address:	GUMI-SI, GYEONGSANGBUK-DO	
City:	GUMI-SI	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	tal Code: 730-710	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14308834

CORRESPONDENCE DATA

Fax Number: (704)945-6735

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 704-945-6700

Email: docket@ahpapatent.com **Correspondent Name:** MELISSA B. PENDLETON

Address Line 1: 11610 N. COMMUNITY HOUSE ROAD

Address Line 2: SUITE 200

Address Line 4: CHARLOTTE, NORTH CAROLINA 28277

ATTORNEY DOCKET NUMBER:	ORNEY DOCKET NUMBER: 1224.130	
AME OF SUBMITTER: MELISSA B. PENDLETON		
SIGNATURE:	/Melissa B. Pendleton/	
DATE SIGNED: 06/19/2014		

Total Attachments: 4

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PATENT REEL: 033137 FRAME: 0601

RECORDATION FORM COVER SHEET PATENTS ONLY		
To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.		
1. Name of conveying party(ies) DONG IN HA DONG MIN PARK SEUNG SHIK SHIN	2. Name and address of receiving party(ies) Name: Cheil Industries Inc. Internal Address:	
KYUONG SIK CHIN Additional name(s) of conveying party(ies) attached? Yes No 3. Nature of conveyance/Execution Date(s): Execution Date(s) June 17, 2014	Street Address: 58 Gumi-daero	
Assignment	City: Gumi-si State: Gyungsangbuk-do Country: South Korea Zip: 730-710 Additional name(s) & address(es) attached? Yes No	
A. Patent Application No.(s) 14/308,834	document is being filed together with a new application. B. Patent No.(s) B. Patent No.(s)	
5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved: 1	
Name: Additon, Higgins, Pendleton & Ashe, P.A. Internal Address:	7. Total fee (37 CFR 1.21(h) & 3.41) \$ Authorized to be charged by credit card Authorized to be charged to deposit account	
Street Address: 11610 N. Community House Road, Suite 200	Enclosed None required (government interest not affecting title)	
City: Charlotte	8. Payment Information	
State: NCZip: 28277-2199	a. Credit Card Last 4 Numbers Expiration Date	
Phone Number: 704-945-6700 Fax Number: 704-945-6735 Email Address:	b. Deposit Account Number	
9. Signature: /Melissa B. Pendleton/	June 19, 2014	
Melissa B. Pendleton Name of Person Signing	Total number of pages including cover sheet, attachments, and documents: 4	

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or malled to: Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandría, V.A. 22313-1450

ASSIGNMENT

WHEREAS, I, Dong In HA, a Korean citizen, with a mailing address Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggido, Republic of Korea; Dong Min PARK, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; Seung Shik SHIN, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; and Kyuong Sik CHIN, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in Low Shrinkage Thermoplastic Resin Composition and Molded Article Comprising the Same, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from a Korean application filed on June 28, 2013, under Serial No. 10-2013-0076078, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Cheil Industries Inc., a Korean corporation (hereinafter referred to as "ASSIGNEE"), having a principal place of business at 58 Gumi-daero, Gumi-si, Gyeongsangbuk-do 730-710, Republic of Korea, has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred,

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and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest-and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interestin and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters

Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

As the below named inventor, I hereby declare:

The application for United States Letters Patent being filed concurrently herewith was made or authorized to be made by me.

I believe that I am the original or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in the declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

<u>ob. 17</u> , 2014	The total section of the section of
6- 17 , 2014	Dong In HA By Sol Dong Min PARK
6.17, 2014	Seung Shik SHIN
	지경식 Kyuong Sik CHIN